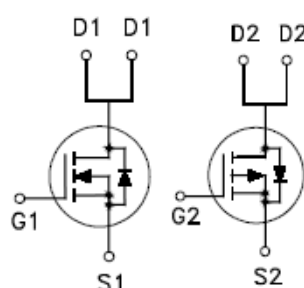


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PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D	Channel
30V	24m Ω @ $V_{GS} = 10V$	20A	N
-30V	60m Ω @ $V_{GS} = -10V$	-12A	P



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	CH.	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	N	30	V
			P	-30	
Gate-Source Voltage		V_{GS}	N	± 20	V
			P	± 20	
Continuous Drain Current ²	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	N	20	A
			P	-12	
	$T_C = 100\text{ }^{\circ}\text{C}$		N	13	
			P	-8	
	$T_A = 25\text{ }^{\circ}\text{C}$		N	7.3	
			P	-4.3	
	$T_A = 70\text{ }^{\circ}\text{C}$		N	5.8	
			P	-3.4	
Pulsed Drain Current ¹		I_{DM}	N	60	A
			P	-30	
Avalanche Current		I_{AS}	N	17.4	A
			P	-18	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	N	15	mJ
			P	16.2	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	N	16	W
			P	15	
	$T_C = 100\text{ }^{\circ}\text{C}$		N	6	
			P	6	

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PARAMETERS/TEST CONDITIONS		SYMBOL	CH.	LIMITS	UNITS
Power Dissipation	T _A = 25 °C	P _D	N	2	W
	T _A = 70 °C		P	1.7	
			N	1.3	
			P	1.1	
Junction & Storage Temperature Range		T _J , T _{STG}		-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	CH.	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$	N	7.5	$^{\circ}\text{C} / \text{W}$
		P	8	
Junction-to-Ambient ³	$R_{\theta JA}$	N	61	
		P	70	

¹Pulse width limited by maximum junction temperature.

²Package limitation current is 30A.

³The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	N	30		V
		$V_{GS} = 0V, I_D = -250\mu A$	P	-30		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	N	1.0	1.5	2.5
		$V_{DS} = V_{GS}, I_D = -250\mu A$	P	-1.0	-1.5	-2.5
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$	N			± 100
		$V_{DS} = 0V, V_{GS} = \pm 20V$	P			± 100
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$	N			1
		$V_{DS} = -24V, V_{GS} = 0V$	P			-1
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55\text{ }^{\circ}C$	N			10
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 55\text{ }^{\circ}C$	P			-10
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 5V, V_{GS} = 10V$	N	60		A
		$V_{DS} = -5V, V_{GS} = -10V$	P	-30		
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 6A$	N		25	38
		$V_{GS} = -4.5V, I_D = -3.5A$	P		54	85
		$V_{GS} = 10V, I_D = 8A$	N		17	24
		$V_{GS} = -10V, I_D = -4.5A$	P		38	60

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PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT	
			MIN	TYP	MAX		
STATIC							
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 8A	N		22		S
		V _{DS} = -10V, I _D = -4.5A	P		11		
DYNAMIC							
Input Capacitance	C _{iss}	N-Channel V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	N		591		pF
			P		548		
Output Capacitance	C _{oss}	P-Channel V _{GS} = 0V, V _{DS} = -15V, f = 1MHz	N		77		
			P		87		
Reverse Transfer Capacitance	C _{rss}		N		65		
			P		86		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz	N		3.5		Ω
			P		12		
Total Gate Charge ²	Q _g	N-Channel V _{DS} = 0.5V _{(BR)DSS} , V _{GS} = 10V, I _D = 8A	N		13		nC
			P		14		
Gate-Source Charge ²	Q _{gs}	P-Channel V _{DS} = 0.5V _{(BR)DSS} , V _{GS} = -10V, I _D = -4.5A	N		2.5		
			P		2		
Gate-Drain Charge ²	Q _{gd}		N		3.4		
			P		3.5		
Turn-On Delay Time ²	t _{d(on)}	N-Channel V _{DS} = 15V I _D ≅ 1A, V _{GS} = 10V, R _G = 6Ω	N		14		nS
			P		16		
Rise Time ²	t _r		N		10		
			P		13		
Turn-Off Delay Time ²	t _{d(off)}	P-Channel V _{DS} = -15V I _D ≅ -1A, V _{GS} = -10V, R _G = 6Ω	N		30		
			P		35		
Fall Time ²	t _f		N		10		
			P		14		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _J = 25 °C)							
Forward Voltage ¹	V _{SD}	I _F = 8A, V _{GS} = 0V	N			1	V
		I _F = -4.5A, V _{GS} = 0V	P			-1.1	
Reverse Recovery Time	t _{rr}	I _F = 8A, dI _F /dt = 100A / μS I _F = -4.5A, dI _F /dt = 100A / μS	N		12.4		nS
			P		16.7		
Reverse Recovery Charge	Q _{rr}		N		3.2		nC
			P		4.5		

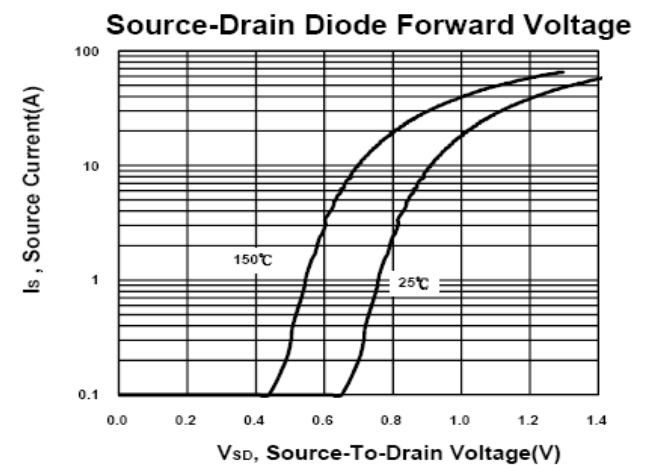
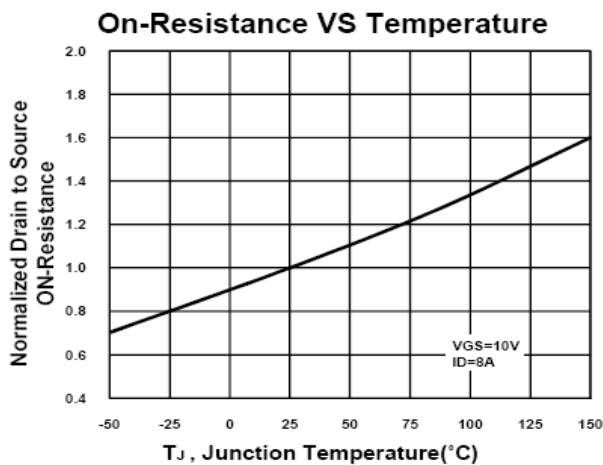
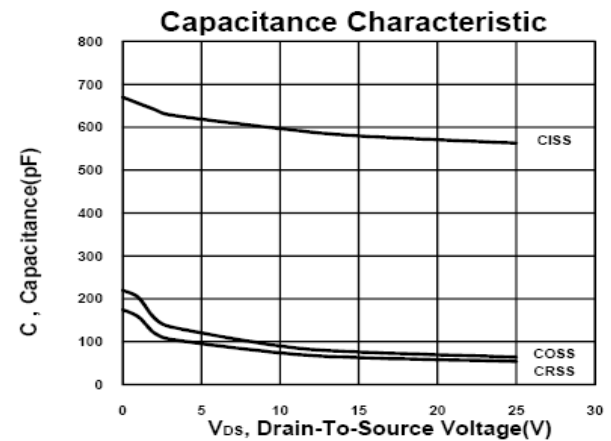
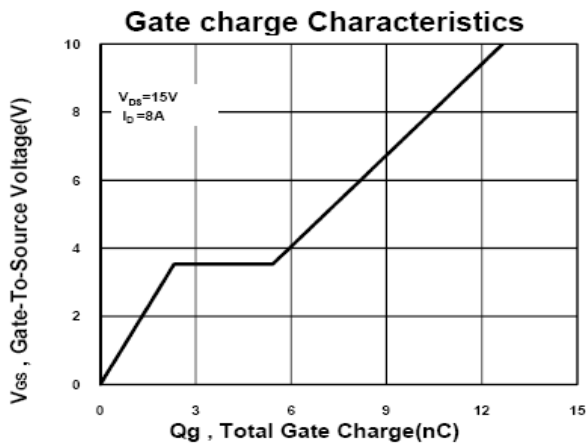
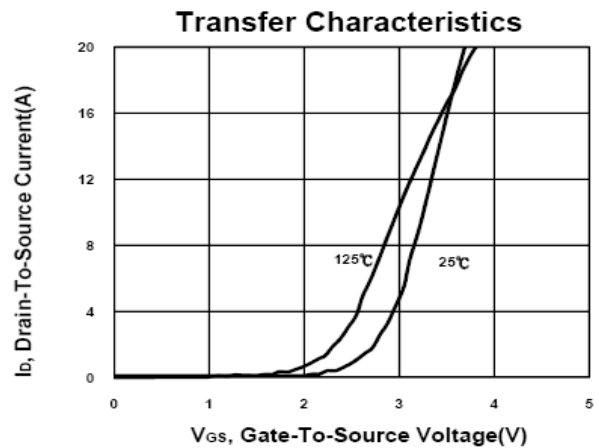
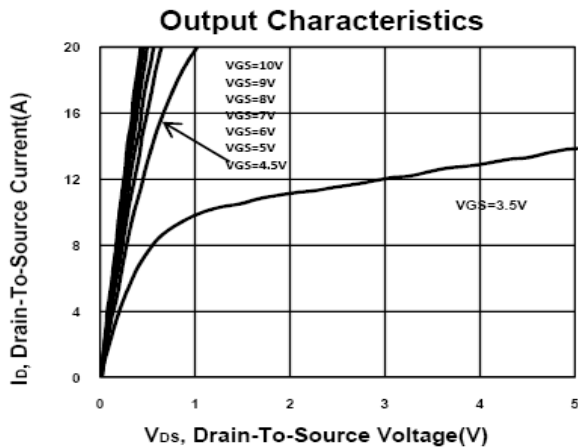
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

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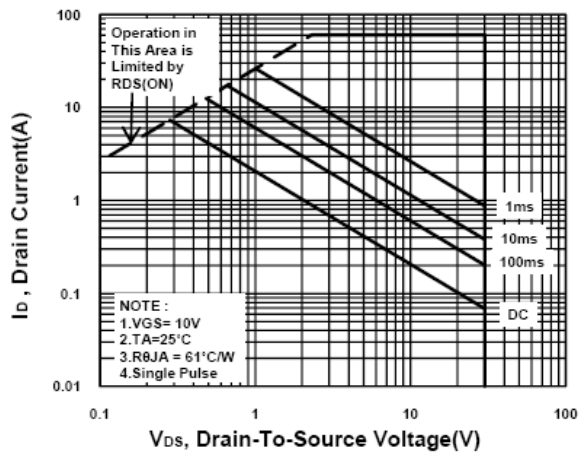
TYPICAL PERFORMANCE CHARACTERISTICS N-CHANNEL



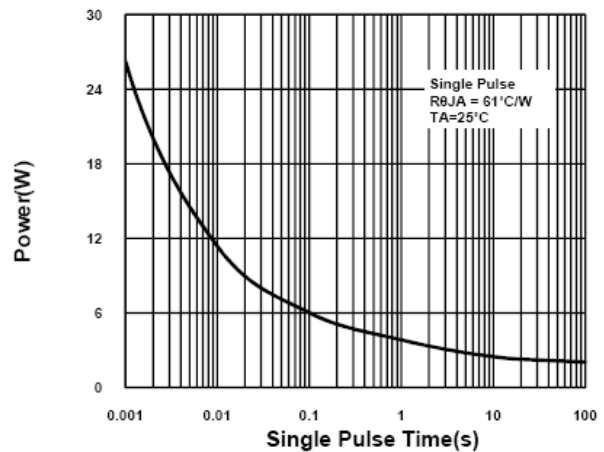
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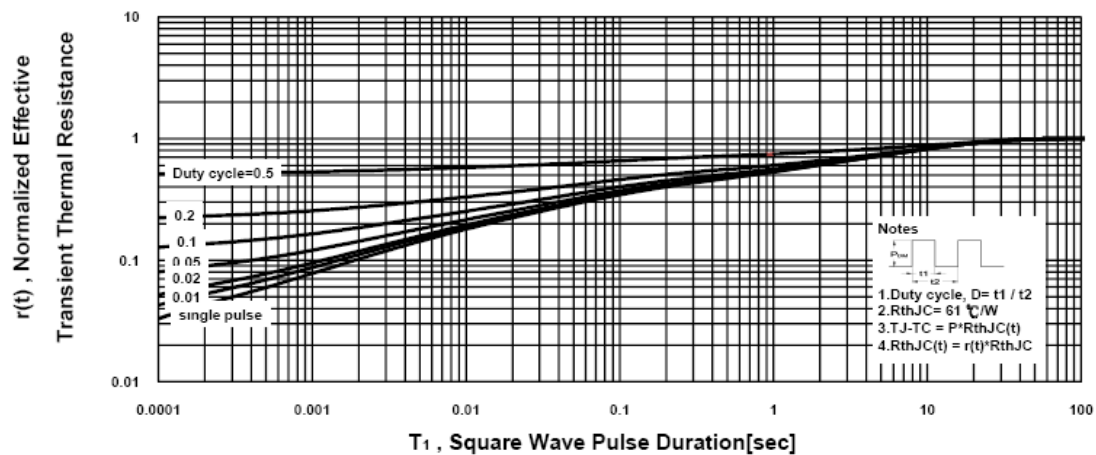
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

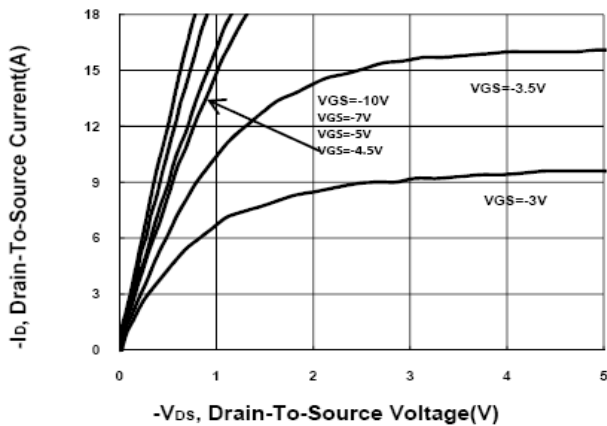


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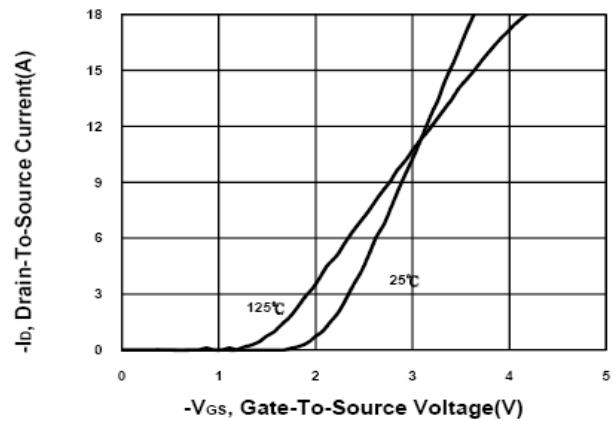
N&P-Channel Enhancement Mode MOSFET

P-CHANNEL

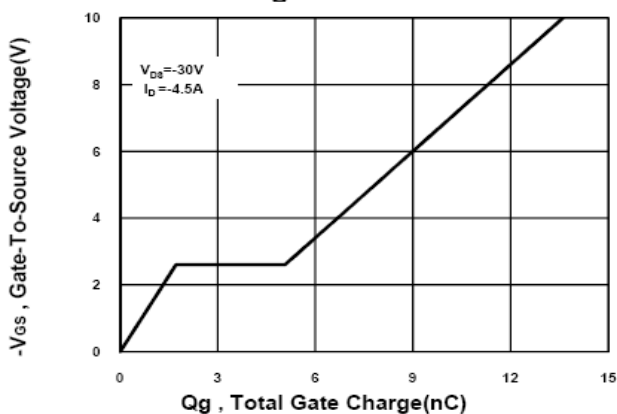
Output Characteristics



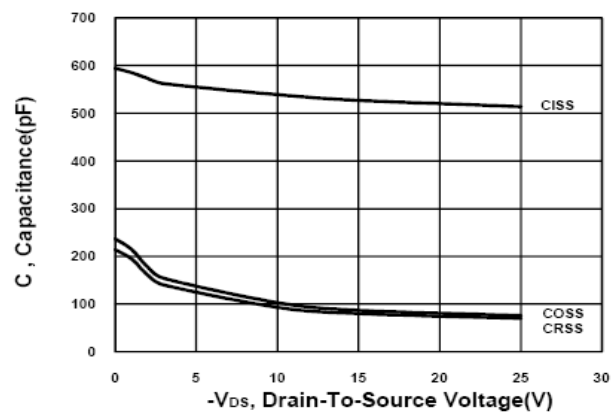
Transfer Characteristics



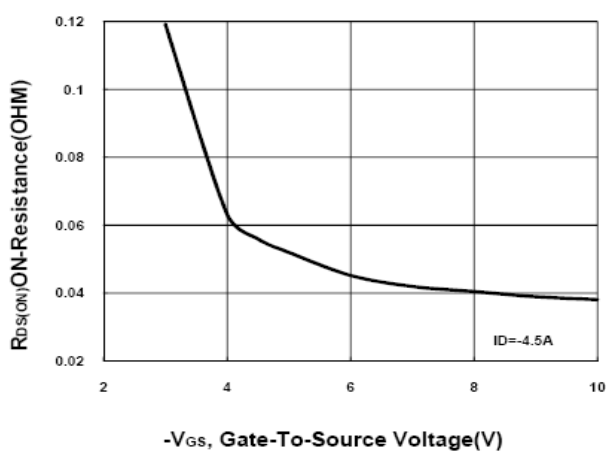
Gate charge Characteristics



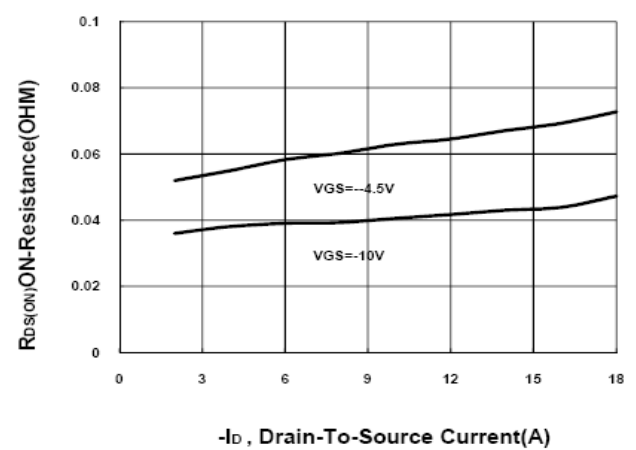
Capacitance Characteristic



On-Resistance VS Gate-To-Source



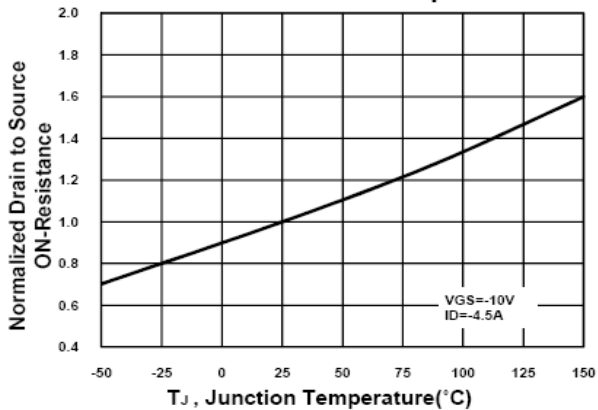
On-Resistance VS Drain Current



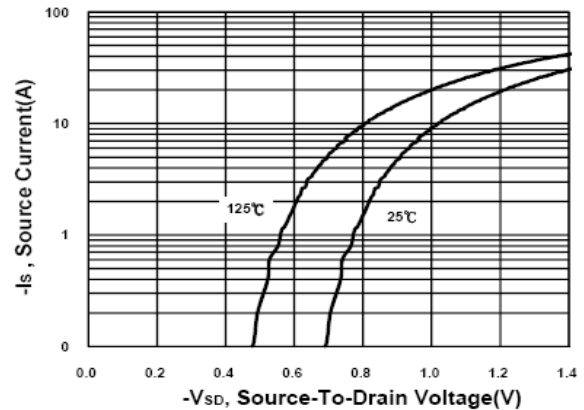
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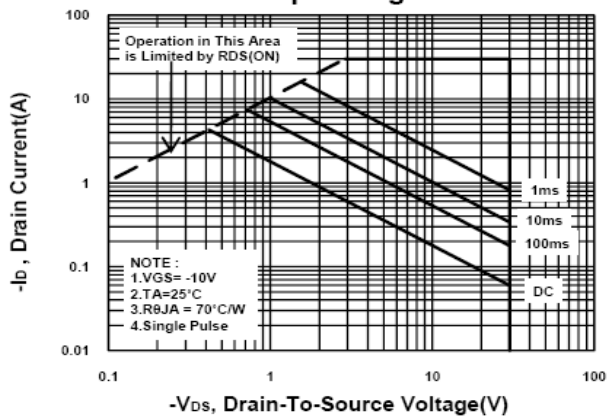
On-Resistance VS Temperature



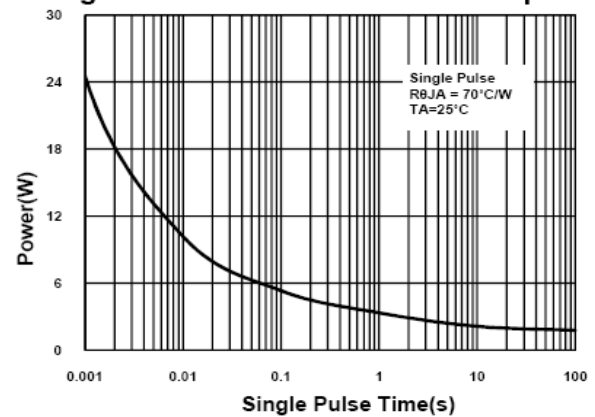
Source-Drain Diode Forward Voltage



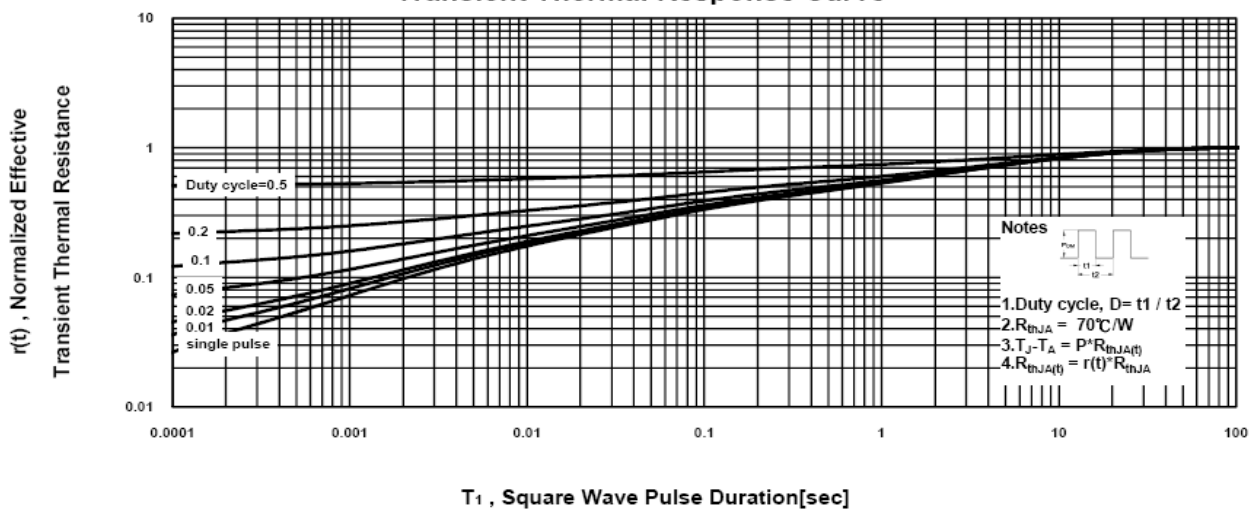
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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Package Dimension

PDFN 3x3P(Dual) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	3.2	3.3	3.4	I	0.7	0.75	0.8
B	2.95	3.05	3.15	J	0.1	0.15	0.25
C	2.95	3.05	3.15	K	0.35		
D		2.29		L	0°	10°	12°
E	3.2	3.3	3.4	M	0.27	0.32	0.37
F		0.13		N		0.65	
G	1.7	1.83	1.96	O		0.2	
H	0.3	0.4	0.5	P	0.06	0.13	0.2

